

ABSTRACT

A device for holding a semiconductor wafer, which is adapted for use in an apparatus for treating a semiconductor wafer under predetermined heating conditions while holding the wafer at a predetermined position within a chamber. The device comprises a susceptor formed in its surface with a wafer loading area for supporting a semiconductor wafer from its back side, and a plurality of support pins provided with a resilient mechanism and arranged at four equiangularly spaced positions on the circumference of at least one concentric circle in the wafer loading area so as to protrude from the surface of the susceptor to support the back surface of the wafer at the forward ends thereof. The support pins on the circle are positioned to support the wafer along the crystal orientation $\langle 110 \rangle$ with respect to the crystal plane (100) of the wafer.